**3GPP** **TSG SA WG 3 Meeting 104-e draft\_S3-212477-r1**

**e-Meeting, 16-27 August 2021**

**Title:** Reply LS to SA6 on new SID on Application Enablement for Data Integrity Verification Service in IoT

**Response to:** S6-211496

**Source:** 3GPP SA3

**To:** 3GPP SA6

**CC:** 3GPP SA1

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**Attachment:**

**1. Overall Description:**

SA3 thanks SA6 for the LS on new SID on application enablement for data integrity verification service in IoT.

SA3 would like to offer the following comments and/or clarifications regarding the new SID in S6-211481:

Based on the justification and objectives in the SA6 SID, SA3 believes the security aspects on data integrity and data integrity verification (e.g. SEAL, CAPIF, data integrity verification in IoT, etc) should be addressed by SA3.

Since the study on application enablement for data integrity verification service in IoT has been endorsed by SA6, SA3 suggests SA6 to proceed with the SID and identify application architecture requirements (i.e. application enablement and service APIs to 3rd party SPs). SA3 will further access the security aspects as stated in clause 8 of the SID based on the output of SA6, if any.

**2. Actions:**

**To SA6:**

SA3 kindly asks SA6 to take the above information into account, and keep SA3 informed if there are any progress on this issue.

**3. Dates of Next SA3 Meetings:**

SA3#105 08 – 12 November 2021 Sophia Antipolis, FR

SA3#106 07 – 11 February 2022 EU